



CES series Reliability test results

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No.	Test Item	Testing conditions	Conditions of acceptability	Number of samples	Number of failures
1	Heat cycle test	(1) -40°C ~ 125°C 30minutes each (2) 800cycles	(1)No degradation of electric characteristics after test. (2)No crack at solder joint.	10	0
2	High temperature/ High humidity bias test	(1) Ta=85°C,RH=85% (2) At rated input (3) Load 0% (4) 500hours	(1)No degradation of electric characteristics after test.	3	0
3	Vibration test	(1) f=10~55Hz,49.0m/s ² (5G) (2) 3minutes period (3) 1hour each X,Y and Z axis	(1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No marked damage of appearance.	3	0
4	Impact test	(1) 196.1m/s ² (20G),11ms (2) Once each X,Y and Z axis	(1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No marked damage of appearance.	3	0
5	Soldering heat test	(1) Soldering 260°C,15seconds (2) Mounting board : t=1.6mm / FR-4	(1)No crack at solder joint. (2)No marked damage of appearance.	1	0
6	Pin strength	(1) Weight : 1.0kg (2) Bending angle : 90 deg. , total 180 deg. (3) No.of cycles : 1 cycle	(1)No degradation of electric characteristics after test. (2)No degradation of terminal	1	0